

Sx230-M242
Environment Test Report

Test Start : 2019,9,30
Test End : 2019,10,30

Tested by:

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Approved by:

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Ver 1.0

Oct. 30, 2019

1. LOW TEMPERATURE/HUMIDITY OPERATING TEST(PASS)	2
2. HIGH TEMPERATURE/HUMIDITY OPERATING TEST(PASS)	4
3. LOW TEMPERATURE NON-OPERATING TEST(PASS)	6
4. HIGH TEMPERATURE NON-OPERATING TEST(PASS)	8

1. Low Temperature/Humidity Operating Test(PASS)

1.1 Testing Objective

To meet the varied temperature requirements from the different areas because products may be subjected to varied operation temperature condition. The product must be tested to verify its temperature endurance.

1.2 Testing Procedure

1. Inspect the component (DUT) to establish operation pretest criteria and physical condition.
2. Connect the component (DUT) to the motherboard and verify its functionality for baseline.
3. Put the component (DUT) into chamber and the motherboard is outside then power on the motherboard.
4. Program the test profile and turn on the chamber based on specification.
5. Inspect the component (DUT) and compare it to pretest data and physical condition.
If any physical issue or malfunction happened during the testing ,this should be recorded and reported.

1.3 Testing Component (DUT)

1pc SM230-M242 128GB

1.4 Testing Equipment

KSON THS-A6T-150 Temperature/Humidity chamber



1.5 Testing Software

Running PassMark Burn-In Test Tool V8 Pro

1.6 Testing Location

Apacer QT Reliability & Environment Test Lab

1.7 Testing Specification

Operating Test

Test Item	Temperature (°C)	Humidity (%)	Time	Remark
Function Test	25	50	10 minutes	-
Function Test	25->20	50->5	2 hours	-
Function Test	20	5	2 hours	-
Function Test	20->-40	5->-	1 hour	-
Function Test	-40	-	96 hours	-
Function Test	-40->25	-->50	1hour 5minutes	-
Function Test	25	50	2 hours	-

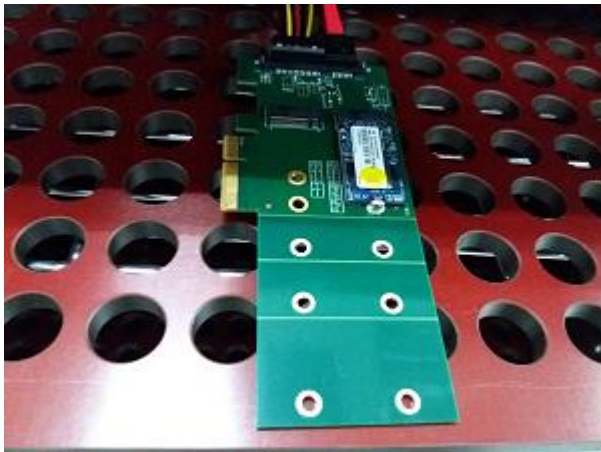
1.8 Testing Criteria

1. Function works normally.
2. No crack on soldering, components.
3. No deformity on components.
4. No rust on metal parts.

1.9 Testing Result

Testing Condition	Temperature	Testing Time	Result	Remark
			Sample No. 1	
Operation	-40°C	96 hours	Pass	-

1.10 Testing Photo



2. High Temperature/Humidity Operating Test(PASS)

2.1 Testing Objective

To meet the varied temperature requirements from the different areas because products may be subjected to varied operation temperature condition. The product must be tested to verify its temperature endurance.

2.2 Testing Procedure

1. Inspect the component (DUT) to establish operation pretest criteria and physical condition.
2. Connect the component (DUT) to the motherboard and verify its functionality for baseline.
3. Put the component (DUT) into chamber and the motherboard is outside then power on the motherboard.
4. Program the test profile and turn on the chamber based on specification.
5. Inspect the component (DUT) and compare it to pretest data and physical condition.
If any physical issue or malfunction happened during the testing ,this should be recorded and reported.

2.3 Testing Component (DUT)

1pc SM230-M242 128GB

2.4 Testing Equipment

KSON THS-A6T-150 Temperature/Humidity chamber



2.5 Testing Software

Running PassMark Burn-In Test Tool V8 Pro

2.6 Testing Location

Apacer QT Reliability & Environment Test Lab

2.7 Testing Specification

Operating Test

Test Item	Temperature (°C)	Humidity (%)	Time	Remark
Function Test	25	50	10 minutes	-
Function Test	25->85	50	2 hours	-
Function Test	85	50	94 hours	-
Function Test	85	50->95	2 hours	-
Function Test	85	95	2 hours	-
Function Test	85->25	95->50	2 hours	-
Function Test	25	50	2 hours	-

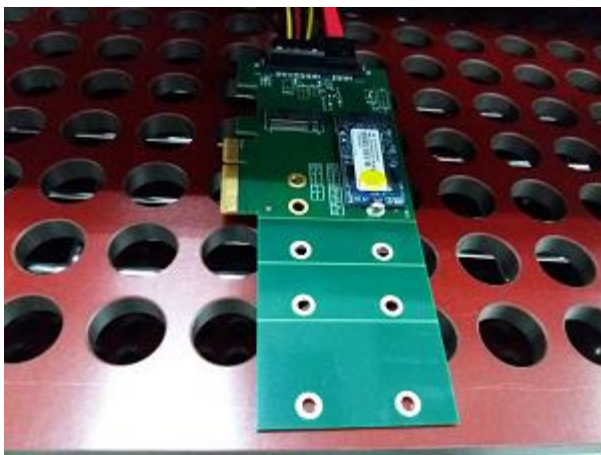
2.8 Testing Criteria

1. Function works normally.
2. No crack on soldering, components.
3. No deformity on components.
4. No rust on metal parts.

2.9 Testing Result

Testing Condition	Temperature/Humidity	Testing Time	Result	Remark
			Sample No. 1	
Operation	85°C/50~95%RH	96 hours	Pass	-

2.10 Testing Photo



3. Low Temperature Non-Operating Test(PASS)

3.1 Testing Objective

To meet the varied temperature requirements from the different areas because products may be subjected to varied operation temperature condition. The product must be tested to verify its temperature endurance.

3.2 Testing Procedure

1. Inspect the component (DUT) to establish operation pretest criteria and physical condition.
2. Connect the component (DUT) to the motherboard and verify its functionality for baseline.
3. Put the component (DUT) into chamber and the motherboard is outside then power on the motherboard.
4. Program the test profile and turn on the chamber based on specification.
5. Inspect the component (DUT) and compare it to pretest data and physical condition.
If any physical issue or malfunction happened during the testing ,this should be recorded and reported.

3.3 Testing Component (DUT)

1pc SM230-M242 128GB

3.4 Testing Equipment

KSON THS-A6T-150 Temperature/Humidity chamber



3.5 Testing Software

Running PassMark Burn-In Test Tool V8 Pro

3.6 Testing Location

Apacer QT Reliability & Environment Test Lab

3.7 Testing Specification

Non-Operating Test

Test Item	Temperature (°C)	Time	Remark
System Off	25	10 minutes	-
System Off	25->-40	1 hour 5minutes	-
System Off	-40	96 hours	-
System Off	-40->25	1 hour 5minutes	-
System Off	25	2 hours	-

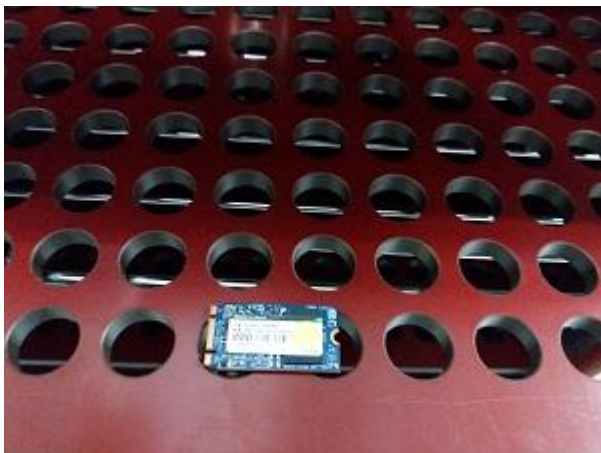
3.8 Testing Criteria

1. Function works normally.
2. No crack on soldering, components.
3. No deformity on components.
4. No rust on metal parts.

3.9 Testing Result

Testing Condition	Temperature	Testing Time	Result	Remark
			Sample No. 1	
Non-Operation	-40°C	96 hours	Pass	-

3.10 Testing Photo



4. High Temperature Non-Operating Test(PASS)

4.1 Testing Objective

To meet the varied temperature requirements from the different areas because products may be subjected to varied operation temperature condition. The product must be tested to verify its temperature endurance.

4.2 Testing Procedure

1. Inspect the component (DUT) to establish operation pretest criteria and physical condition.
2. Connect the component (DUT) to the motherboard and verify its functionality for baseline.
3. Put the component (DUT) into chamber and the motherboard is outside then power on the motherboard.
4. Program the test profile and turn on the chamber based on specification.
5. Inspect the component (DUT) and compare it to pretest data and physical condition.
If any physical issue or malfunction happened during the testing ,this should be recorded and reported.

4.3 Testing Component (DUT)

1pc SM230-M242 128GB

4.4 Testing Equipment

KSON THS-A6T-150 Temperature/Humidity chamber



4.5 Testing Software

Running PassMark Burn-In Test Tool V8 Pro

4.6 Testing Location

Apacer QT Reliability & Environment Test Lab

4.7 Testing Specification

Non-Operating Test

Test Item	Temperature (°C)	Time	Remark
System Off	25	10 minutes	-
System Off	25->100	1 hour 15minutes	-
System Off	100	96 hours	-
System Off	100->25	1 hour 15minutes	-
System Off	25	2 hours	-

4.8 Testing Criteria

1. Function works normally.
2. No crack on soldering,components.
3. No deformity on components.
4. No rust on metal parts.

4.9 Testing Result

Testing Condition	Temperature	Testing Time	Result	Remark
			Sample No. 1	
Non-Operation	100°C	96 hours	Pass	-

4.10 Testing Photo

